18th IEEE Electrical Design of Advanced Packaging and Systems Symposium

EDAPS 2025

December 15th to 17th, 2025, Hokkaido University, Sapporo, Japan

Sponsorship and exhibitor opportunities

EDAPS is the premier international conference in the Asia-Pacific region on advanced and emerging issues in the electrical modeling, analysis, and design of electronic interconnections, packages, and systems. Over three days, the conference will feature the latest advancements in CAD, design, and measurement techniques for:

- ensuring signal, power, and thermal integrity in high-speed systems;
- optimizing performance in high-speed, RF, wireless and quantum systems;
- enabling heterogeneous integration and packaging for chiplets.

EDAPS 2025 will be held at Hokkaido university in Japan.

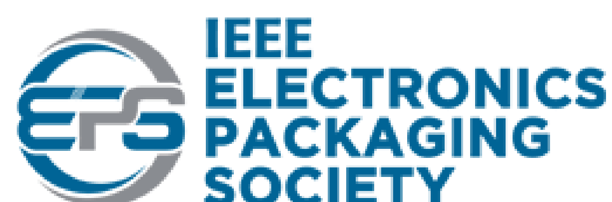
With an estimate of more than 100 participants from industry and academia all over the globe, we believe EDAPS 2025 will be an excellent opportunity for your organization to promote its products/services, strengthen its brand recognition in the leading international venue in the area, connect with experts and potential customers, and recruit top talents. Please find in the next page the sponsorship and exhibitor opportunities that EDAPS 2025 will offer.

We look forward to seeing you at Hokkaido University!

Hideki Sasaki, Rapidus Corporation, General Chair
Seiya Kasai, Hokkaido University, Local Arrangement Chair
Kiyoshi Hasegawa, Rapidus Corporation, Financial Chair

Conference Topics

- ✓ Advanced Packages: 2D, 2.xD, 3D, 3.5D
- ✓ Interposers: Silicon, RDL, Bridge, Glass
- ✓ Interconnects: Hybrid Bonding, uBump, TSV, Carbon Nanotube, Graphene
- ✓ High-Speed Interfaces: UCIe, SerDes, HBM, LPDDR, GDDR, DDR
- ✓ PDN: Backside PDN, Deep Trench Capacitor, IVR
- ✓ EDA: AI-Based Tools, Multi-Physics, ADK
- ✓ Machine Learning, Deep learning, LLM
- ✓ Modeling: Model Order Reduction, Macro-modeling
- ✓ RF/mmWave/Terahertz Antenna and Packages
- ✓ Co-Package Optics (CPO)
- ✓ Power Devices & Modules: GaN/SiC/Diamond
- ✓ EMC/EMI/EMS: ex. Automotive Applications



For more information, please visit http://edaps.org

Packages	Platinum	Gold	Silver	Bronze
Fee (Yen)	1,000,000	800,000	500,000	200,000
Maximum number of sponsors	2	2	-	-
Demo/presentation* in main conference room during lunch time	20 mins	10 mins	-	-
Streaming promotional video* during opening and closing ceremonies, and coffee breaks	✓ main screen	✓ main screen	✓ main screen	✓ sub monitor
Logo* on name card	✓	-	-	-
Space in conference proceedings*	2 pages	2 page	1 page	1/2 page
Promotional brochure or merchandise included in workshop kit*	✓	✓	✓	✓
Logo* and link included in the conference website and proceedings	✓	✓	✓	✓
Exhibition space (table and 2 chairs, electrical socket, wi-fi)	✓	✓	✓	-
Full registrations included	3	2	1	0

*: material to be provided by the sponsors

To register as a sponsor or exhibitor, please email the following contacts.

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Kiyoshi Hasegawa, Rapidus Corporation, Financial Chair,
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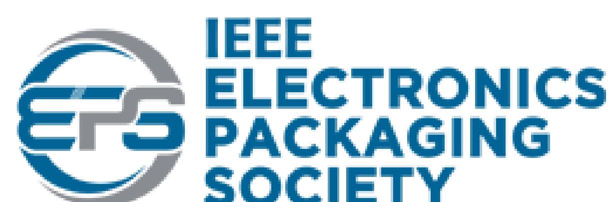

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